



FOR IMMEDIATE RELEASE

Buc, France, November 2007, 20th - **Introduction of 3D Plus Memory Modules in the ESA EPPL Issue 11**

3D Plus is very pleased to announce the introduction of its Catalogue Products in the European Preferred Part List (EPPL) from the European Space Agency (ESA).

The ESA EPPL Issue 11 has been released on November 2007, 16th and includes :

- 16 Mb SRAM Memory Modules, P/N: MMSR16001604S-C
- 4 Gb SDRAM Memory Module, P/N: MMSD08512808S-E
- 4 Mb EEPROM Memory Module, P/N: MMEE085108045SxC

With 12ns access time over the temperature range and its very small package size, 3D Plus 16 Mb SRAM is the fastest Space Qualified SRAM and will answer the requirements of performance and miniaturization of the most demanding Space qualified Computer Applications.

The 4 Gb SDRAM memory modules will fit a wide range of Solid-State-Data Recorder applications as well as high speed computer board for payload electronics. It is today the design reference component and it is flight proven many times in Europe, North America and Asia-Pacific.

The ESA qualified 4 Mb EEPROM features the highest density and the smallest package size available for a Space Qualified Product.

These modules are fully compliant to the 3D Plus [Capability Domain qualified by ESA](#) for Space Application and benefit from a full Radiation Assurance Guarantee (TID, SEL and SEE).

“The introduction of our products in the ESA EPPL is the recognition of the excellent performance, the very high reliability proven in flight for many years and the added value brought to our customers equipments by our catalogue products. This great achievement is a first step. We will continue to develop valuable solution for our Space customers... and we already plan to introduce all of [our shortform products](#) in the next edition of the ESA EPPL” said Pierre-Eric Berthet, 3D Plus Director of Sales and Marketing.

About 3D PLUS company :

Founded in 1996 as a spin-off of Thales, 3D Plus has become a worldwide actor for the advanced high density 3D package and die stacking technology meeting the demand for high reliability, extreme performance and very small size electronics.



Its portfolio of patented and very advanced stacking technologies starts with Package scale upward to chip-size and wafer-level packaging techniques and provides leading edge, highly integrated and rugged modules embedding Active, Passive, Opto-electronics and MEMS/MOEMS components.

With a broad range of catalogue products including memory modules, camera heads, power converters and computer modules, with its very miniaturized System-In-Package solutions and by Licensing its technologies, 3D PLUS meets the requirements of high technology industries in industrial, telecom., computer/blade server, military, avionics, medical and space markets.

With more than 18000 modules in orbit today and a failure-free flight heritage of more than 7 years, 3D Plus is today the largest Space Qualified MCM manufacturer in Europe.

3D Plus products fly in numerous satellite programs for all major space agencies worldwide.

Most of the Space missions launched recently embeds 3D Plus Modules : Corot and SARLupe 06/12, Themis in 02/07, Cosmo in 06/07, Dawn in 09/07....

Current customer portfolio includes the major Aerospace prime contractors and equipment manufacturers spread over 30 countries : EADS, Thales Alenia Space, Boeing, Honeywell, Ball Aerospace, Bae, ESA, CNES, NASA, JPL, NT Space, MELCO, ISRO, KARI, SAAB Space,...

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